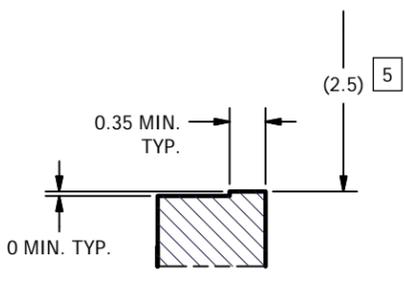
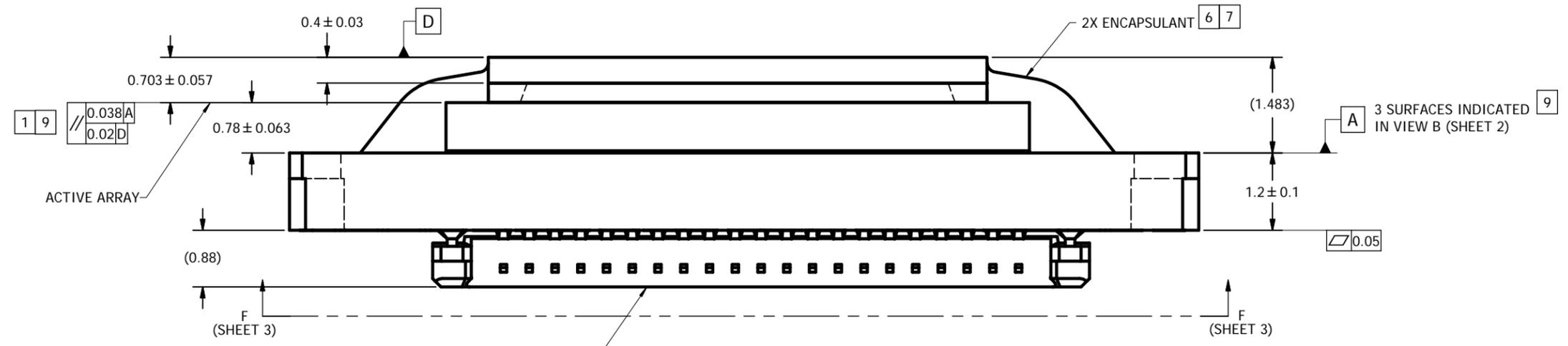
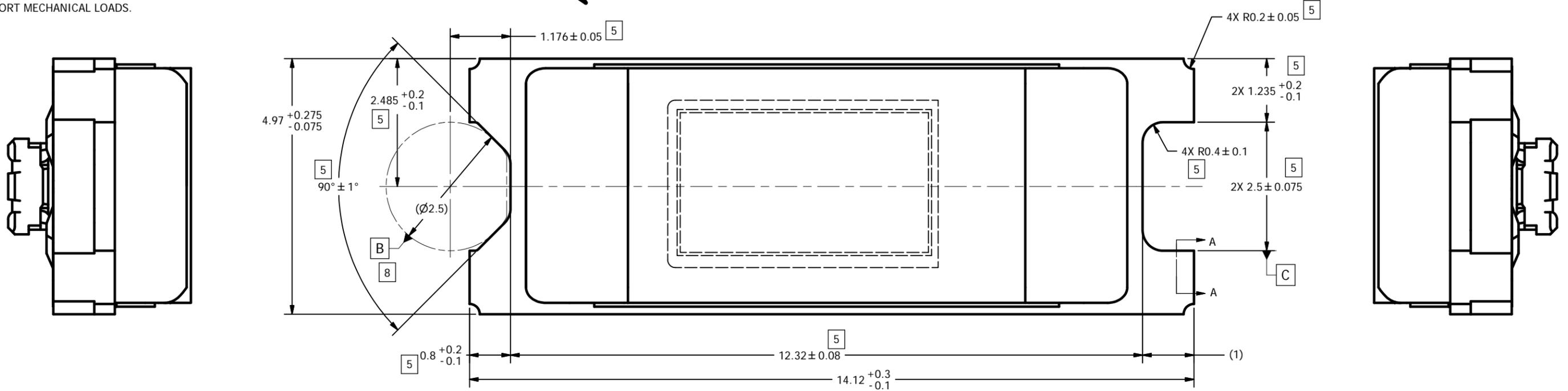


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REVISIONS			
REV	DESCRIPTION	DATE	BY
A	ECO 2100735 INITIAL RELEASE	8/3/09	BMH
B	ECO 2102356 ADD DATUM E AND NOTE 9; UPDATE SOLDER APPEARANCE; TIGHTEN NOTCH X-AXIS TOL'S	10/22/09	BMH
C	ECO 2104056 CHG ENCAP MAX HEIGHT FROM TBD TO ZERO	1/4/10	BMH
D	ECO 2166625 ADD "FQC PACKAGE" TO DRAWING TITLE; SHOW APERTURE CORNER RADII PICTORIALLY	5/30/17	BMH

- NOTES UNLESS OTHERWISE SPECIFIED:
- 1 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY.
 - 2 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.6 DEGREES.
 - 3 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE ARRAY.
 - 4 DMD MARKING TO APPEAR IN CONNECTOR RECESS.
 - 5 NOTCH DIMENSIONS ARE DEFINED BY UPPERMOST LAYERS OF CERAMIC, AS SHOWN IN SECTION A-A.
 - 6 ENCAPSULANT TO BE CONTAINED WITHIN DIMENSIONS SHOWN IN VIEW C (SHEET 2). NO ENCAPSULANT IS ALLOWED ON TOP OF THE WINDOW.
 - 7 ENCAPSULANT NOT TO EXCEED THE HEIGHT OF THE WINDOW.
 - 8 DATUM B IS DEFINED BY A DIA. 2.5 PIN, WITH A FLAT ON THE SIDE FACING TOWARD THE CENTER OF THE ACTIVE ARRAY, AS SHOWN IN VIEW B (SHEET 2).
 - 9 WHILE ONLY THE THREE DATUM A TARGET AREAS A1, A2, AND A3 ARE USED FOR MEASUREMENT, ALL 4 CORNERS SHOULD BE CONTACTED, INCLUDING E1, TO SUPPORT MECHANICAL LOADS.

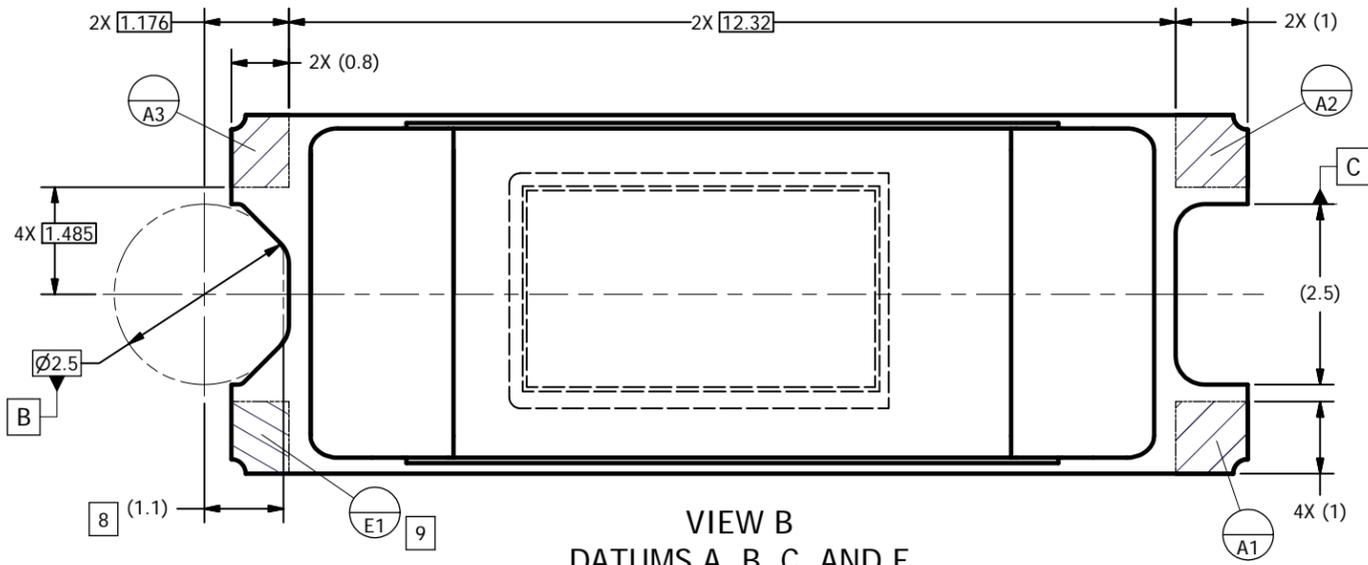


(PANASONIC AXT642124DD1, 42-CONTACT, 0.4 mm PITCH BOARD-TO-BOARD HEADER) INTERFACE TO PANASONIC AXT542124DD1 SOCKET

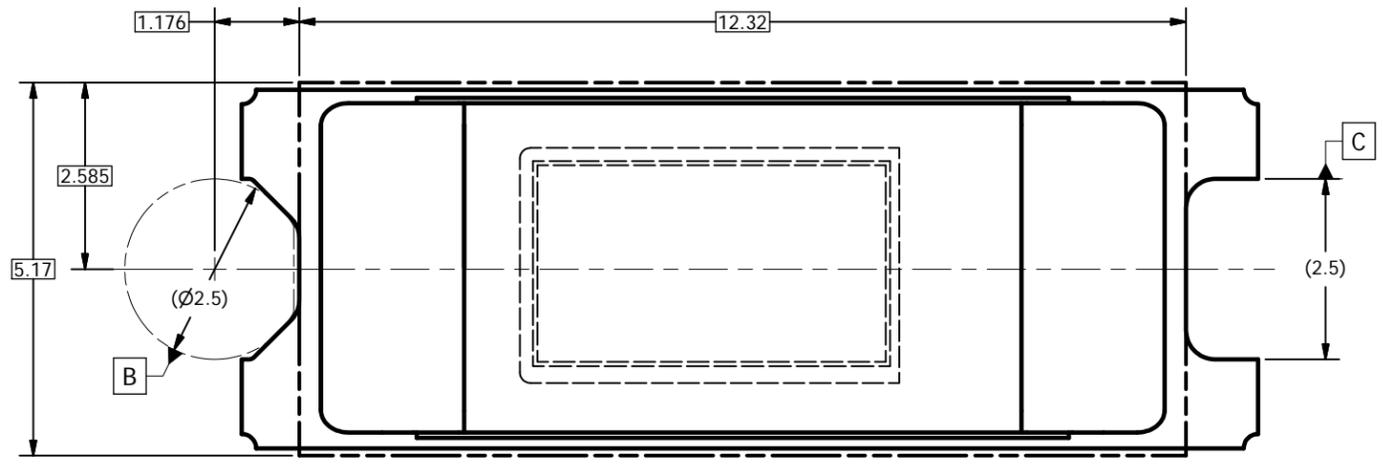
UNLESS OTHERWISE SPECIFIED	
● DIMENSIONS ARE IN MILLIMETERS	
● TOLERANCES:	
ANGLES ± 1°	
2 PLACE DECIMALS ± 0.25	
1 PLACE DECIMALS ± 0.50	
● DIMENSIONAL LIMITS APPLY BEFORE PROCESSES	
● INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994	
● REMOVE ALL BURRS AND SHARP EDGES	
● PARENTHETICAL INFORMATION FOR REFERENCE ONLY	
THIRD ANGLE PROJECTION	NONE
APPLICATION	0314DA USED ON

DRAWN	DATE
B. HASKETT	8/3/2009
ENGINEER	
B. HASKETT	8/3/2009
QA/CE	
P. KONRAD	8/3/2009
CM	
F. ARMSTRONG	8/3/2009
APPROVED	
J. GRIMMETT	8/3/2009

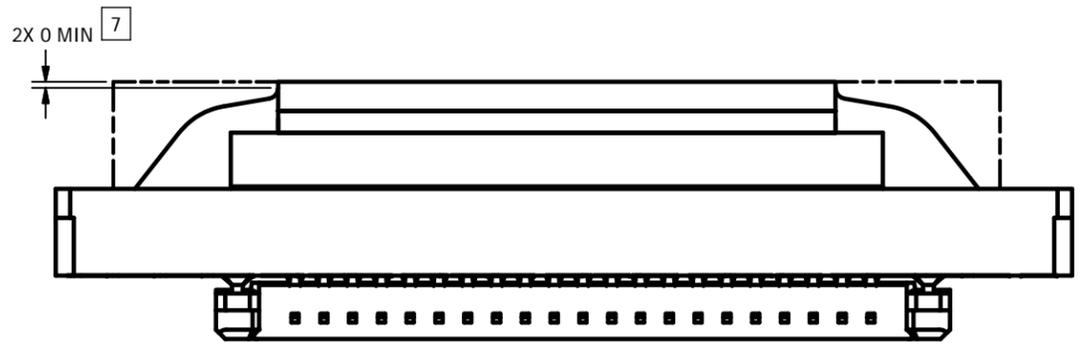
		TITLE	
		ICD, MECHANICAL, DMD, .2 nHD DDR SERIES 230 (FQC PACKAGE)	
SIZE	DWG NO.	REV	
D	2510560	D	
SCALE	SHEET		OF
25:1	1		3



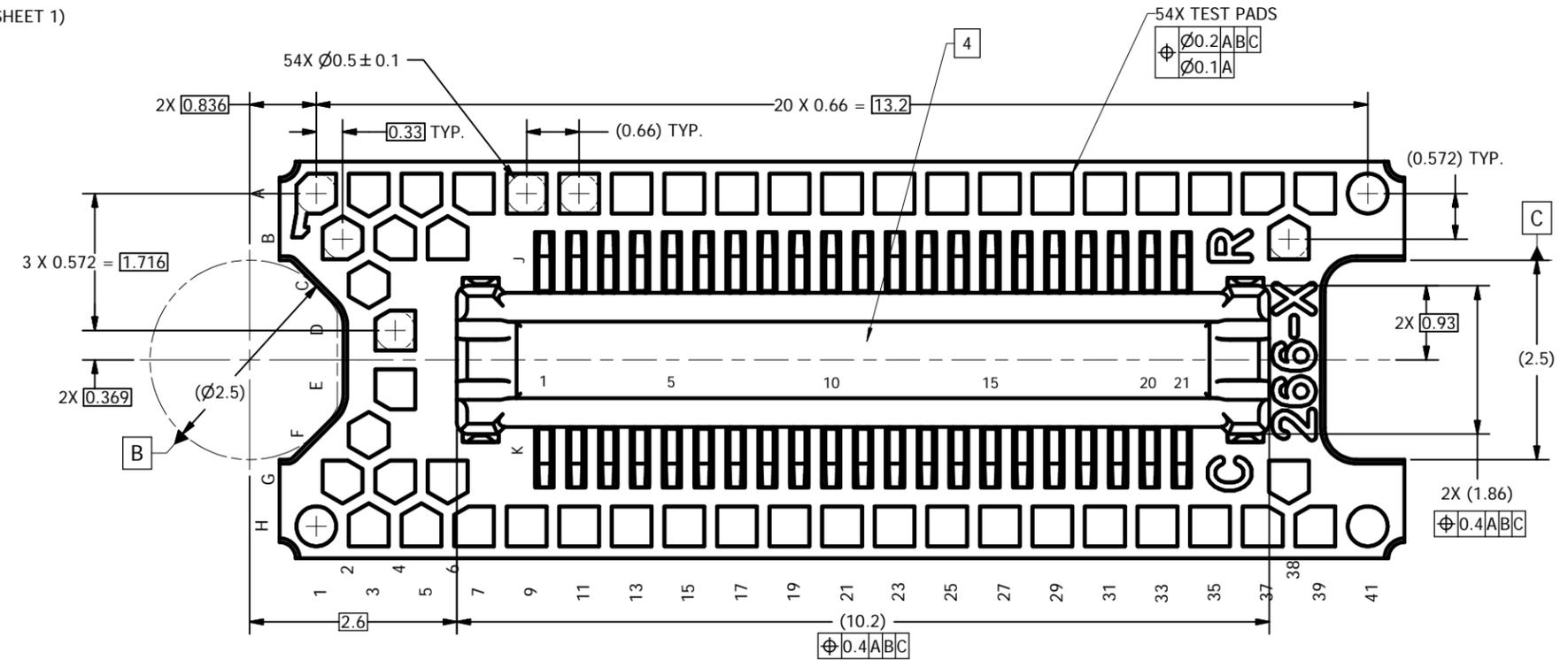
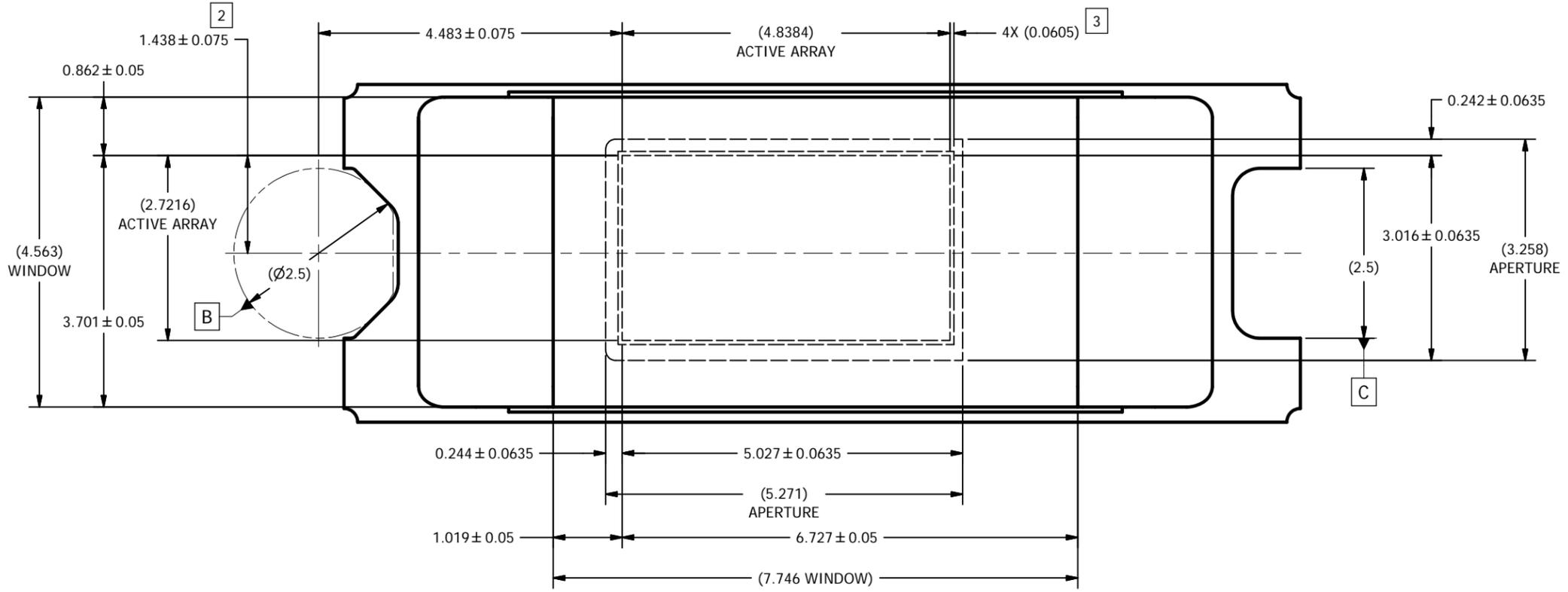
VIEW B
 DATUMS A, B, C, AND E
 SCALE 20 : 1
 (FROM SHEET 1)



VIEW C 6
 ENCAPSULANT MAXIMUM X/Y DIMENSIONS
 SCALE 20 : 1
 (FROM SHEET 1)



VIEW D
 ENCAPSULANT MAXIMUM HEIGHT
 SCALE 20 : 1



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